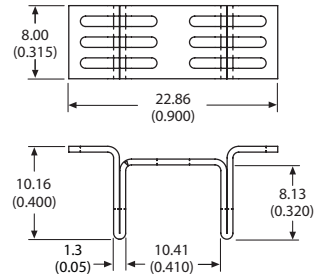
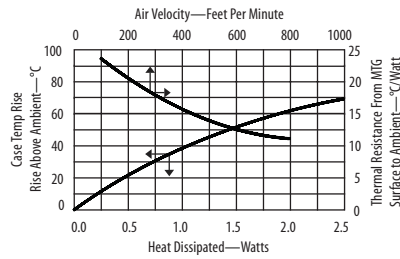


5731 Surface mount heat sink for D-PAK (TO-252) package semiconductors



Surface mount heat sink for D-PAK (TO-252) package semiconductors remove the heat indirectly without contacting the device like traditional through hole heat sinks. The device and the heat sink are soldered directly to a modified drain pad creating a thermal transfer path from package tab to the heat sink.



Material: 0.63 (0.025) Thick Copper
Finish: Tin Plated

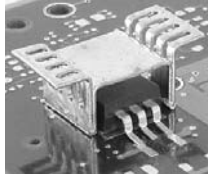
Refer to Figure A and B on page 26 for board footprint information

ORDERING INFORMATION

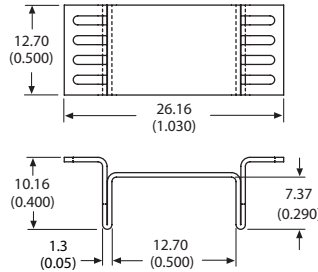
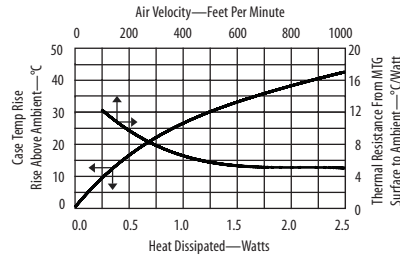
Part Number	Packaging
573100D00010G	13" Reel, 250 per reel
573100D00000G	Bulk, 500 per bag

See page 25 for tape and reel information

5733 Surface mount heat sink for D² PAK (TO-263) package semiconductors



Surface mount heat sink for D² PAK (TO-263) package semiconductors remove the heat indirectly without contacting the device like traditional through hole heat sinks. The device and the heat sink are soldered directly to a modified drain pad creating a thermal transfer path from package tab to the heat sink.



Material: 0.63 (0.025) Thick Copper
Finish: Tin Plated

Refer to Figure A and B on page 26 for board footprint information

ORDERING INFORMATION

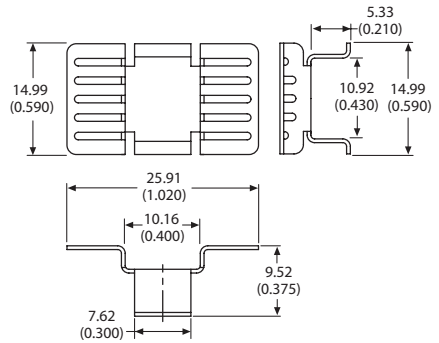
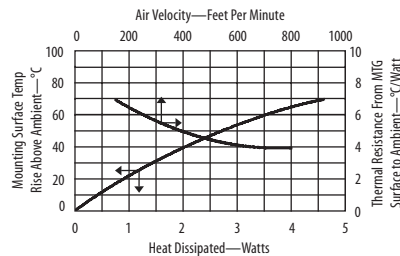
Part Number	Packaging
573300D00010G	13" Reel, 250 per reel
573300D00000G	Bulk, 500 per bag

See page 25 for tape and reel information

7106 Surface mount heat sink for D² PAK (TO-263), power SO-10 (MO-184) and SO-10 package semiconductors



Surface mount heat sink for D² PAK (TO-263), power SO-10 (MO-184) and SO-10 package semiconductors remove the heat indirectly without contacting the device like traditional through hole heat sinks. The device and the heat sink are soldered directly to a modified drain pad creating a thermal transfer path from package tab to the heat sink.



Material: 0.63 (0.025) Thick Copper
Finish: Tin Plated

Refer to Figure C on page 26 for board footprint information

ORDERING INFORMATION

Part Number	Packaging
7106D/TRG	13" Reel, 200 per reel
7106DG	Bulk, 500 per bag

See page 25 for tape and reel information

7109 Surface mount heat sink for D² PAK (TO-263) package semiconductors

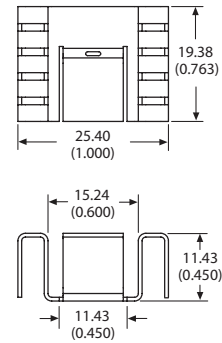
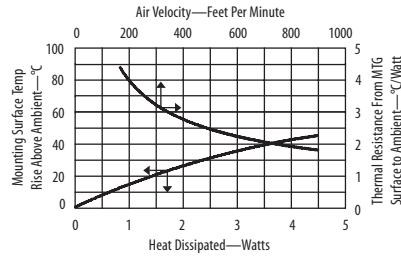


Surface mount heat sink for D² PAK (TO-263) package semiconductors remove the heat indirectly without contacting the device like traditional through hole heat sinks. The device and the heat sink are soldered directly to a modified drain pad creating a thermal transfer path from package tab to the heat sink.

ORDERING INFORMATION

Part Number	Packaging
7109D/TRG	13" Reel, 125 per reel
7109DG	Bulk, 500 per bag

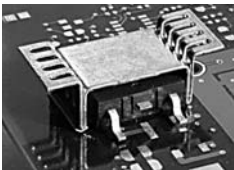
See below for tape and reel information



Refer to Figure D on page 26 for board footprint information

Material: 0.63 (0.025) Thick Copper
Finish: Tin Plated

5734 Surface mount heat sink for D³ PAK (TO-268) package semiconductors

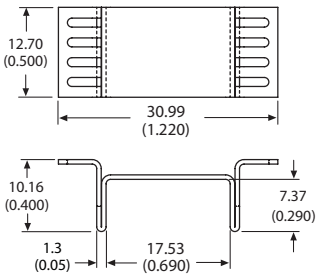
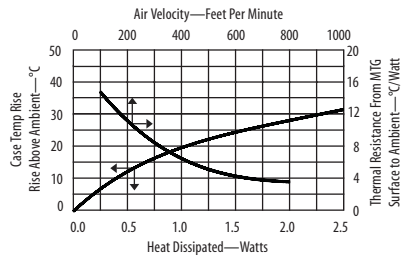


Surface mount heat sink for D³ PAK (TO-268) package semiconductors remove the heat indirectly without contacting the device like traditional through hole heat sinks. The device and the heat sink are soldered directly to a modified drain pad creating a thermal transfer path from package tab to the heat sink.

ORDERING INFORMATION

Part Number	Packaging
573400D00010G	13" Reel, 250 per reel
573400D00000G	Bulk, 500 per bag

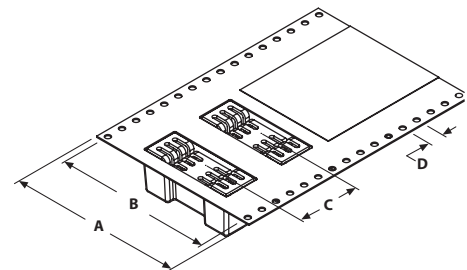
See below for tape and reel information



Refer to Figure A and B on page 26 for board footprint information

Material: 0.63 (0.025) Thick Copper
Finish: Tin Plated

Tape and Reel information



ORDERING INFORMATION

Part Number	"A" Dim	"B" Dim	"C" Dim	"D" Dim
7106D/TRG	44.00 (1.730)	40.40 (1.590)	24.00 (0.940)	4.06 (0.160)
7109D/TRG	44.00 (1.730)	40.40 (1.590)	36.00 (1.420)	4.06 (0.160)
573100D00010G	44.00 (1.730)	40.40 (1.590)	16.00 (0.630)	4.06 (0.160)
573300D00010G	44.00 (1.730)	40.40 (1.590)	24.00 (0.940)	4.06 (0.160)
573400D00010G	44.00 (1.730)	40.40 (1.590)	24.00 (0.940)	4.06 (0.160)